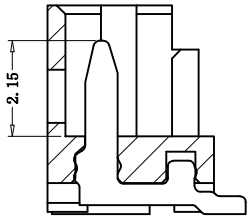
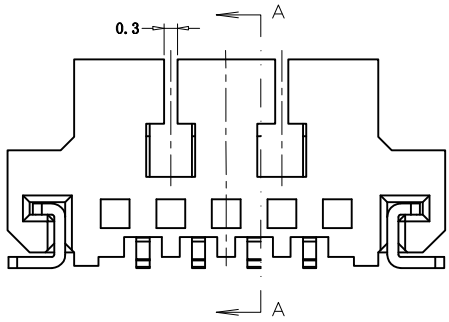
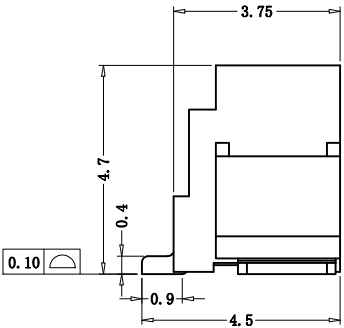
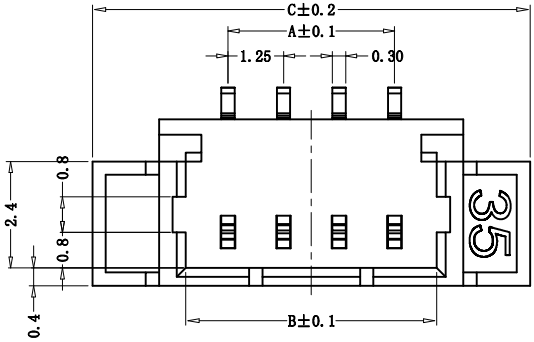
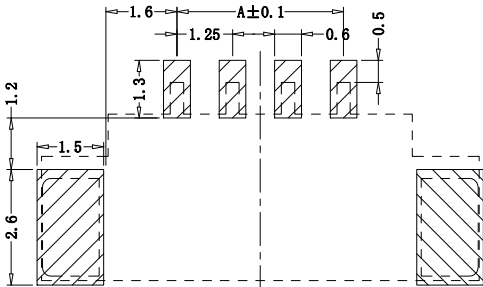
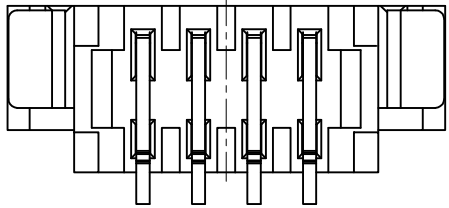


REV.	ECN NO.	LOCAS.	DESCRIPTION	DATE	DESIGN
A			NEW DRAWING		

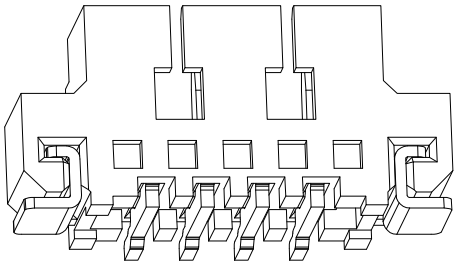
孔位	A	B	C
2	1.25	3.10	7.35
3	2.50	4.35	8.60
4	3.75	5.60	9.85
5	5.00	6.85	11.10
6	6.25	8.10	12.35
7	7.50	9.35	13.60
8	8.75	10.60	14.85
9	10.00	11.85	16.10
10	11.25	13.10	17.35
11	12.50	14.35	18.60
12	13.75	15.60	19.85
13	15.00	16.85	21.10
14	16.25	18.10	22.35
15	17.50	19.35	23.60
16	18.75	20.60	24.85
17	20.00	21.85	26.10
18	21.25	23.10	27.35
19	22.50	24.35	28.60
20	23.75	25.60	29.85



SECTION A—A



PC BOARD LAYOUT



技术要求(Technical Index):

- 材质与表面处理(Material And Finish):
基座 (Housing) : LCP UL94V-0 Nature Or Black;
端子 (Terminal) :Copper Alloy Au/Sn Plated;
焊片 (Solder) : Copper Alloy Au/Sn Plated;
- 工作温度(Temperature range): -20° C~+85° C.
- 额定电压(Rated voltage): 100V, AC/DC.
- 额定电流: 1A, AC/DC.
- 接触电阻(Contact resistance): ≤20mΩ.
- 绝缘电阻(Insulation resistance): ≥500MΩ.
- 耐电压(Withstanding Voltage):500V AC/minute.

DESIGN:		Xiping Huang			广东国连电子有限公司			
CHECK:		Ke Tian			GUANGDONG GUOLIAN ELECTRONICS CO.,LTD			
APPROVED:		Youquan Xu			TITLE:			
DIM	TOL	DIM	TOL	1. 25mm 条形连接器立贴开口				
X.	±0.25			PART NO.				
X. X	±0.20	X°.	±3.0°					
X. XX	±0.15	X. X°		1. 25-C-nPB-***				
X. XXX		X. XX°						
REV. A		SCALE: N/A		UNIT:	SHEET:			
				mm	1/1			